

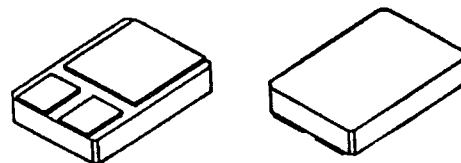
14849 Firestone Boulevard · La Mirada, CA 90638  
Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424

**Designer's Data Sheet****FEATURES:**

- Rugged construction with poly silicon gate
- Low RDS(on) and high transconductance
- Excellent high temperature stability
- Very fast switching speed
- Fast recovery and superior dv/dt performance
- Increased reverse energy capability
- Low input and transfer capacitance for easy paralleling
- Hermetically sealed power surface mount package
- TX, TXV and Space Level screening available
- Replaces: IRF140 Types

**SFF140**

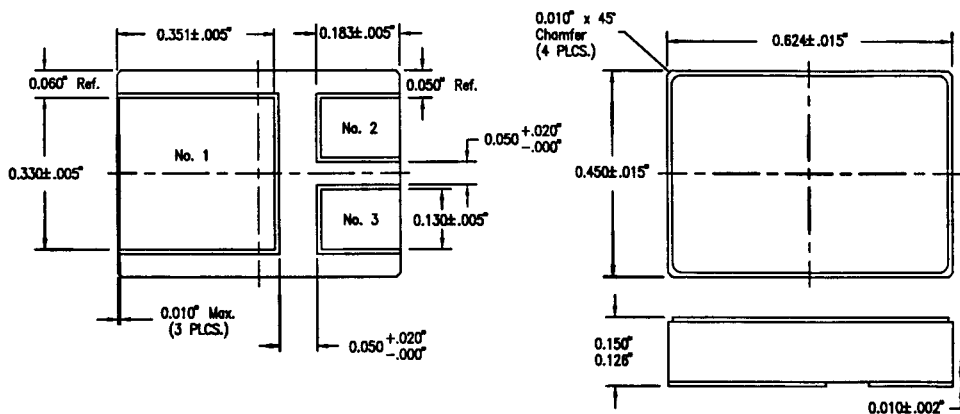
**28 AMP  
100 VOLT  
0.077  $\Omega$   
N-CHANNEL  
POWER MOSFET**

**MILPACK****MAXIMUM RATINGS:**

CHARACTERISTIC	SYMBOL	VALUE	UNIT
Drain to Source Voltage	$V_{DS}$	100	Volts
Gate to Source Voltage	$V_{GS}$	$\pm 20$	Volts
Continuous Drain Current	$I_D$	28	Amps
Operating and Storage Temperature	Top & Tstg	-55 to +175	$^{\circ}\text{C}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.7	$^{\circ}\text{C/W}$
Total Device Dissipation @ $T_C=25^{\circ}\text{C}$	$P_D$	74	Watts
Total Device Dissipation @ $T_C=55^{\circ}\text{C}$		56	

**PACKAGE OUTLINE: MILPACK****PIN OUT:**

**PIN 1: DRAIN  
PIN 2: SOURCE  
PIN 3: GATE**



**NOTE:** All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.

**DATA SHEET #: F00037 C****MED**

## SFF140

SOLID STATE DEVICES, INC

14849 Firestone Boulevard · La Mirada, CA 90638  
Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424**ELECTRICAL CHARACTERISTICS @  $T_J=25^{\circ}\text{C}$  (Unless Otherwise Specified)**

RATING	SYMBOL	MIN	TYP	MAX	UNIT
Drain to Source Breakdown Voltage ( $V_{GS}=0\text{ V}$ , $I_D=250\mu\text{A}$ )	$BV_{DSS}$	100	---	---	V
Drain to Source on State Resistance ( $V_{GS}=10\text{ V}$ , $I_D=60\%$ Rated ID)	$R_{DS(on)}$	---	0.06	0.077	$\Omega$
On State Drain Current ( $V_{DS} > I_D(on) \times R_{DS(on)}$ Max, $V_{GS}=10\text{ V}$ )	$I_D(on)$	28	---	---	A
Gate Threshold Voltage ( $V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$ )	$V_{GS(th)}$	2.0	2.4	4.0	V
Forward Transconductance ( $V_{DS} > I_D(on) \times R_{DS(on)}$ Max, $I_{DS}=60\%$ rated ID)	$g_{fs}$	8.7	13	---	S( $\Omega$ )
Zero Gate Voltage Drain Current ( $V_{DS}=\text{max rated voltage}$ , $V_{GS}=0\text{ V}$ ) ( $V_{DS}=80\%$ rated VDS, $V_{GS}=0\text{ V}$ , $T_A=150^{\circ}\text{C}$ )	$I_{DSS}$	---	---	250 1000	$\mu\text{A}$
Gate to Source Leakage Forward Gate to Source Leakage Reverse	At rated VGS $I_{GSS}$	---	---	100 -100	nA
Total Gate Charge Gate to Source Charge Gate to Drain Charge	$V_{GS}=10\text{ Volts}$ 50% rated VDS Rated ID $Q_g$ $Q_{gs}$ $Q_{gd}$	---	40 8 19	60 12 28	nC
Turn on Delay Time Rise Time Turn Off Delay Time Fall Time	$V_{DD}=50\%$ rated VDS rated ID $R_G=9.1\Omega$ $t_d(on)$ $t_r$ $t_d(off)$ $t_f$	---	15 72 40 50	23 110 60 75	nsec
Diode Forward Voltage ( $I_S=\text{rated ID}$ , $V_{GS}=0\text{ V}$ , $T_J=25^{\circ}\text{C}$ )	$V_{SD}$	---	1.3	2.5	V
Diode Reverse Recovery Time Reverse Recovery Charge	$T_J=25^{\circ}\text{C}$ $I_F=10\text{A}$ $dI/dt=100\text{ A}/\mu\text{sec}$ $t_{rr}$ $Q_{RR}$	70 0.44	150 0.91	300 1.9	nsec $\mu\text{C}$
Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{GS}=0\text{ Volts}$ $V_{DS}=25\text{ Volts}$ $f=1\text{ MHz}$ $C_{iss}$ $C_{oss}$ $C_{rss}$	---	1500 500 90	---	pF

SAFE OPERATING AREA (S.O.A.)  
 $T_C = 25^{\circ}\text{C}$ , D.C. CONDITION